

# Doppel-NPN-Silizium-Fototransistor mit Tageslichtsperrfilter

## Dual Silicon NPN Phototransistor with Daylight-Cutoff Filter

### SFH 3160 F



#### Wesentliche Merkmale

- Tageslichtsperrfilter
- Doppel-Fototransistor übereinander positioniert
- Doppel-Fototransistor mit gemeinsamem Kollektor
- Optimale Kombination mit SFH4111 (vertikaler Enkoder)

#### Anwendungen

- Richtungserkennung
- Empfänger in Lichtschranken
- Bandende-Erkennung (z.B. Videorecorder)
- Positionsüberwachung
- Barcode-Leser
- „Messen/Steuern/Regeln“
- Münzzähler

#### Features

- Daylight Filter
- Dual Phototransistor positioned one on top of each other
- Dual Phototransistor with common Collector
- Ideal combination with SFH4111 (vertical encoder)

#### Applications

- Direction detection
- Detector in photointerrupters
- Tape end detection
- Position sensing
- Barcode reader
- For control and drive circuits
- Coin counters

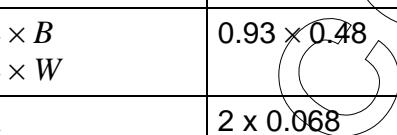
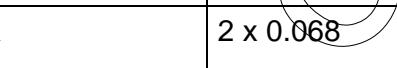
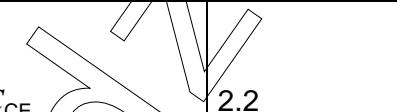
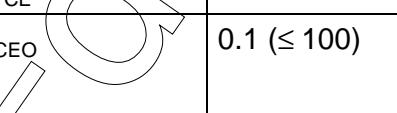
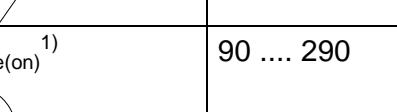
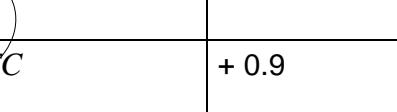
Typ Type	Bestellnummer Ordering Code	$I_{ce(on)}$ [ $\mu A$ ] $V_{ce}=3.5V$ , 950nm, $E_e=0.34mW/cm^2$
SFH 3160 F	Q62702-P5296	90 ... 290

**Grenzwerte**  
**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}; T_{stg}$	- 40 ... + 85	°C
Löttemperatur bei Tauchlötzung Lötstelle $\geq$ 2 mm vom Gehäuse, Lötzeit $t \leq 5$ s Dip soldering temperature $\geq$ 2 mm distance from case bottom, soldering time $t \leq 5$ s	$T_s$	260	°C
Löttemperatur bei Kolbenlötzung Lötstelle $\geq$ 2 mm vom Gehäuse, Lötzeit $t \leq 3$ s Iron soldering temperature $\geq$ 2 mm distance from case bottom, soldering time $t \leq 3$ s	$T_s$	300	°C
Kollektor-Emitterspannung Collector-emitter voltage	$V_{CE}$	30	V
Kollektorstrom Collector current	$I_c$	5	mA
Kollektorspitzenstrom, $t < 10 \mu\text{s}$ Collector surge current	$I_{cs}$	10	mA
Emitter-Kollektorspannung Emitter-collector voltage	$V_{EC}$	7	V
Verlustleistung, $T_A = 25$ °C Total power dissipation	$P_{tot}$	100	mW
Wärmewiderstand Sperrsicht - Umgebung Thermal resistance junction - ambient	$R_{thJA}$	450	K/W

Kennwerte ( $T_A = 25^\circ\text{C}$ ,  $\lambda = 950 \text{ nm}$ )

Characteristics

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S \max}$	920	nm
Spektraler Bereich der Fotoempfindlichkeit $S = 10\%$ von $S_{\max}$ Spectral range of sensitivity $S = 10\%$ of $S_{\max}$	$\lambda$	780 ... 1100	nm
Abmessungen der Chip-Fläche Dimension of chip area	$L \times B$ $L \times W$		mm × mm
Bestrahlungsempfndliche Fläche Radiant sensitive area	$A$		mm <sup>2</sup>
Halbwinkel Half angle	$\phi$		Grad deg.
Kapazität Capacitance $V_{CE} = 3V, f = 1 \text{ MHz}, E = 0$	$C_{CE}$		pF
Dunkelstrom Dark current $V_{CE} = 10 \text{ V}$	$I_{CEO}$		nA
Fotostrom Photocurrent $E_e = 0.34 \text{ mW/cm}^2, V_{CE} = 3.5 \text{ V}$	$I_{e(on)}^{(1)}$		μA
Temperaturkoeffizient von $I_{e(on)}$ Temperature coefficient of $I_{e(on)}$ $V_{ce} = 5 \text{ V}$	$\mathcal{T}C$		%/K

<sup>1)</sup>  $I_{e(on)}$  ist der Mittelwert der Emitterströme der beiden Fototransistoren. $I_{e(on)}$  is the mean value of the emitter currents of the two phototransistors.

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Emitterstrom-Verhältnis der 2 Fototransistoren Emitter current ratio of the 2 phototransistors $V_{ce} = 3.5V, E_e = 0.34mW/cm^2$	$R^1)$	1 ... 1.1	
Übersprechen zwischen T1 und T2 Crosstalk between T1 and T2 $E_e = 0.34 \text{ mW/cm}^2, \lambda = 950\text{nm}, V_{CE} = 3.5 \text{ V}$	$(Ie1 - Ie1')/Ie1^2)$	3	%
Anstiegszeit/Abfallzeit Rise and fall time $I_C = 1 \text{ mA}, V_{CC} = 5 \text{ V}, R_L = 1 \text{ k}\Omega$	$t_r$ $t_f$	7 9	$\mu\text{s}$
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage $I_C = 50\mu\text{A}$ , $E_e = 0.5 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	$V_{CEsat}$	0.1 ( $\leq 0.4$ )	V

<sup>1)</sup>  $Ie(\text{max})/Ie(\text{min})$

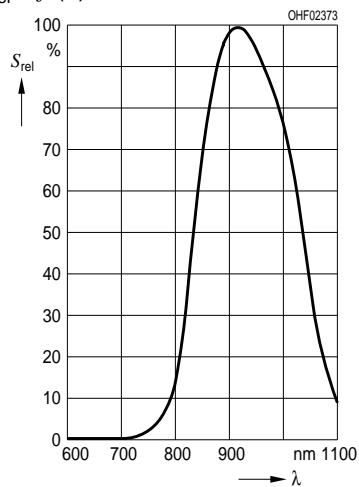
<sup>2)</sup> Testing condition

a)  $Ie1$  measured while the emitter of T2 is grounded

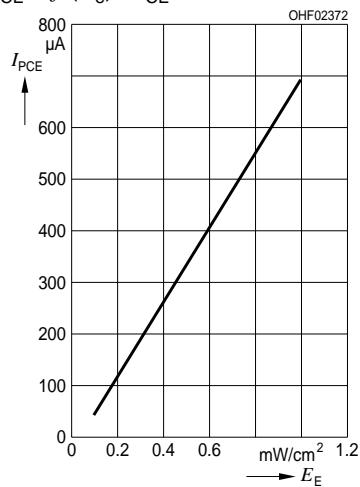
b)  $Ie1'$  is the  $Ie1$  reading while the emitter of T2 is not connected

**OSRAM**

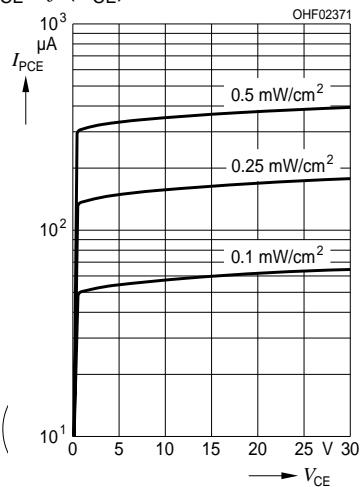
**Relative Spectral Sensitivity**  
 $S_{\text{rel}} = f(\lambda)$



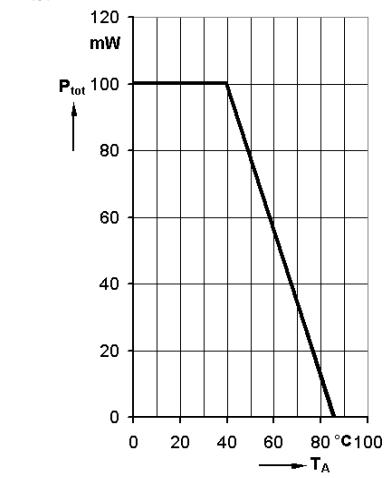
**Photocurrent**  
 $I_{\text{PCE}} = f(E_e), V_{\text{CE}} = 5 \text{ V}$



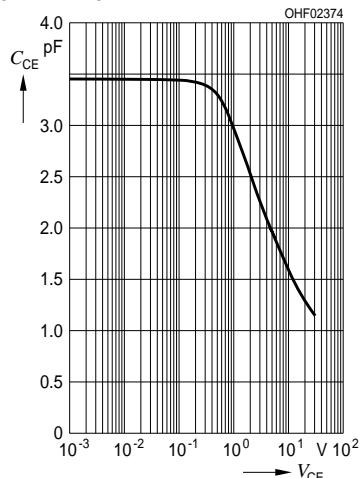
**Photocurrent SFH 3160 F**  
 $I_{\text{PCE}} = f(V_{\text{CE}})$



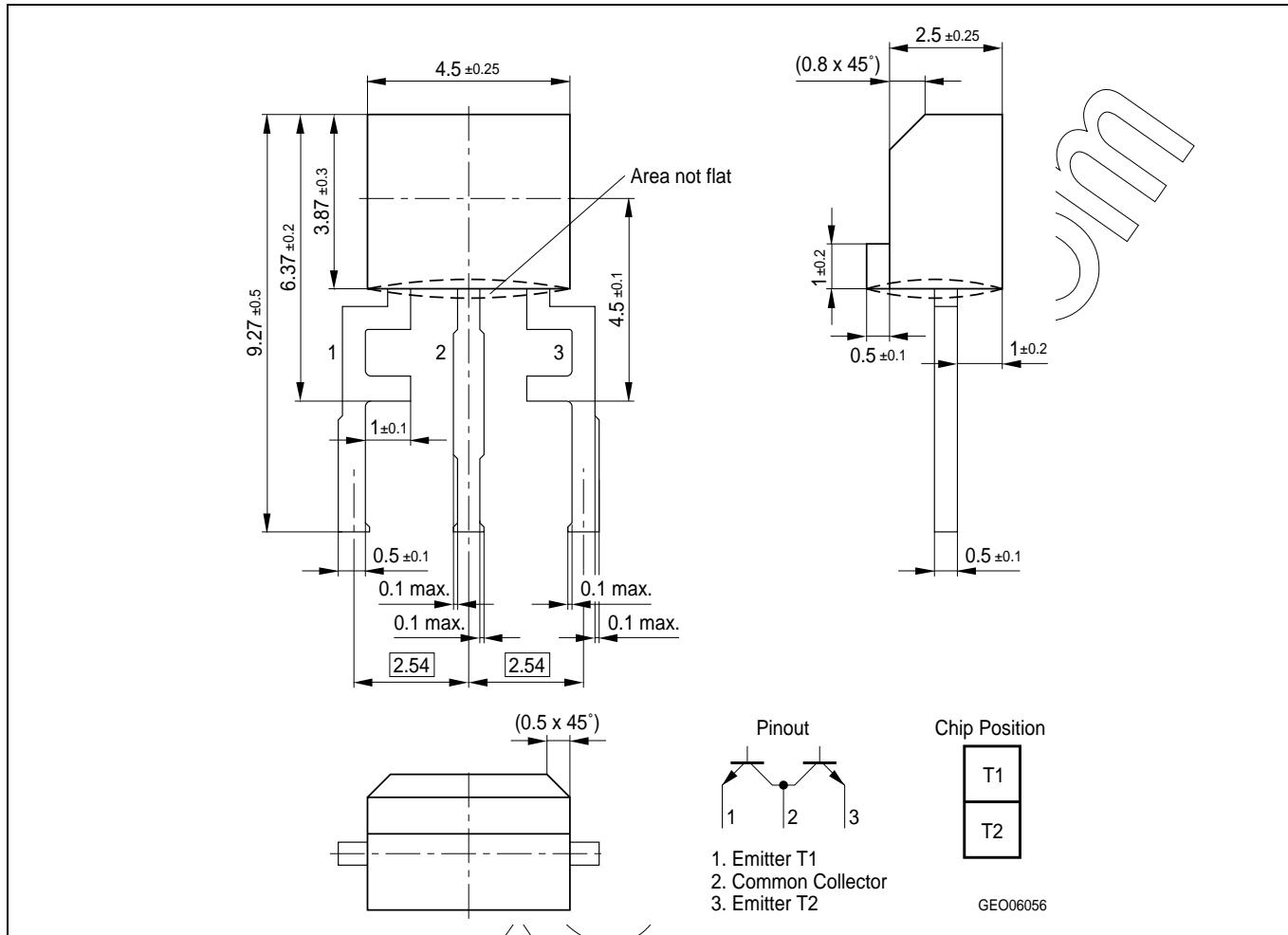
**Total Power Dissipation**  
 $P_{\text{tot}} = f(T_A)$



**Collector-Emitter Capacitance**  
 $C_{\text{CE}} = f(V_{\text{CE}}), f = 1 \text{ MHz}, E = 0$



## Maßzeichnung Package Outlines



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

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